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Understanding [Embedded - Microprocessors](#)

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of [Embedded - Microprocessors](#)

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details

Product Status	Obsolete
Core Processor	MIPS32
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	350MHz
Co-Processors/DSP	-
RAM Controllers	DDR
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10/100Mbps (1)
SATA	-
USB	-
Voltage - I/O	3.3V
Operating Temperature	-40°C ~ 85°C (TA)
Security Features	-
Package / Case	256-LBGA
Supplier Device Package	256-CABGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/79rc32h434-350bcgi

Signal	Type	Name/Description
DDRCKP	O	DDR Positive DDR clock. This signal is the positive clock of the differential DDR clock pair.
DDRCSN	O	DDR Chip Selects. This active low signal is used to select DDR device(s) on the DDR bus.
DDRDATA[15:0]	I/O	DDR Data Bus. 16-bit DDR data bus is used to transfer data between the RC32434 and the DDR devices. Data is transferred on both edges of the clock.
DDRDM[1:0]	O	DDR Data Write Enables. Byte data write enables are used to enable specific byte lanes during DDR writes. DDRDM[0] corresponds to DDRDATA[7:0] DDRDM[1] corresponds to DDRDATA[15:8]
DDRDSQS[1:0]	I/O	DDR Data Strobes. DDR byte data strobes are used to clock data between DDR devices and the RC32434. These strobes are inputs during DDR reads and outputs during DDR writes. DDRDSQS[0] corresponds to DDRDATA[7:0] DDRDSQS[1] corresponds to DDRDATA[15:8]
DDRRASN	O	DDR Row Address Strobe. The DDR row address strobe is asserted during DDR transactions.
DDRVREF	I	DDR Voltage Reference. SSTL_2 DDR voltage reference is generated by an external source.
DDRWEN	O	DDR Write Enable. DDR write enable is asserted during DDR write transactions.
PCI Bus		
PCIAD[31:0]	I/O	PCI Multiplexed Address/Data Bus. Address is driven by a bus master during initial PCIFRAMEN assertion. Data is then driven by the bus master during writes or by the bus target during reads.
PCICBEN[3:0]	I/O	PCI Multiplexed Command/Byte Enable Bus. PCI commands are driven by the bus master during the initial PCIFRAMEN assertion. Byte enable signals are driven by the bus master during subsequent data phase(s).
PCICLK	I	PCI Clock. Clock used for all PCI bus transactions.
PCIDEVSELN	I/O	PCI Device Select. This signal is driven by a bus target to indicate that the target has decoded the address as one of its own address spaces.
PCIFRAMEN	I/O	PCI Frame. Driven by a bus master. Assertion indicates the beginning of a bus transaction. Negation indicates the last data.
PCIGNTN[3:0]	I/O	PCI Bus Grant. In PCI host mode with internal arbiter: The assertion of these signals indicates to the agent that the internal RC32434 arbiter has granted the agent access to the PCI bus. In PCI host mode with external arbiter: PCIGNTN[0]: asserted by an external arbiter to indicate to the RC32434 that access to the PCI bus has been granted. PCIGNTN[3:1]: unused and driven high. In PCI satellite mode: PCIGNTN[0]: This signal is asserted by an external arbiter to indicate to the RC32434 that access to the PCI bus has been granted. PCIGNTN[3:1]: unused and driven high.
PCIIRDYN	I/O	PCI Initiator Ready. Driven by the bus master to indicate that the current datum can complete.

Table 1 Pin Description (Part 2 of 6)

Signal	Type	Name/Description
PCILOCKN	I/O	PCI Lock. This signal is asserted by an external bus master to indicate that an exclusive operation is occurring.
PCIPAR	I/O	PCI Parity. Even parity of the PCIAD[31:0] bus. Driven by the bus master during address and write Data phases. Driven by the bus target during the read data phase.
PCIPERRN	I/O	PCI Parity Error. If a parity error is detected, this signal is asserted by the receiving bus agent 2 clocks after the data is received.
PCIREQN[3:0]	I/O	PCI Bus Request. In PCI host mode with internal arbiter: These signals are inputs whose assertion indicates to the internal RC32434 arbiter that an agent desires ownership of the PCI bus. In PCI host mode with external arbiter: PCIREQN[0]: asserted by the RC32434 to request ownership of the PCI bus. PCIREQN[3:1]: unused and driven high. In PCI satellite mode: PCIREQN[0]: this signal is asserted by the RC32434 to request use of the PCI bus. PCIREQN[1]: function changes to PCIIDSEL and is used as a chip select during configuration read and write transactions. PCIREQN[3:2]: unused and driven high.
PCIRSTN	I/O	PCI Reset. In host mode, this signal is asserted by the RC32434 to generate a PCI reset. In satellite mode, assertion of this signal initiates a warm reset.
PCISERRN	I/O	PCI System Error. This signal is driven by an agent to indicate an address parity error, data parity error during a special cycle command, or any other system error. Requires an external pull-up.
PCISTOPN	I/O	PCI Stop. Driven by the bus target to terminate the current bus transaction. For example, to indicate a retry.
PCITRDYN	I/O	PCI Target Ready. Driven by the bus target to indicate that the current data can complete.
General Purpose Input/Output		
GPIO[0]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: U0SOUT Alternate function: UART channel 0 serial output.
GPIO[1]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: U0SINP Alternate function: UART channel 0 serial input.
GPIO[2]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: U0RTSN Alternate function: UART channel 0 request to send.
GPIO[3]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: U0CTSN Alternate function: UART channel 0 clear to send.

Table 1 Pin Description (Part 3 of 6)

Signal	Type	Name/Description
GPIO[4]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: MADDR[22] Alternate function: Memory and peripheral bus address.
GPIO[5]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: MADDR[23] Alternate function: Memory and peripheral bus address.
GPIO[6]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: MADDR[24] Alternate function: Memory and peripheral bus address. The value of this pin may be used as a counter timer clock input (see Counter Timer Clock Select Register in Chapter 14, Counter/Timers, of the RC32434 User Manual).
GPIO[7]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: MADDR[25] Alternate function: Memory and peripheral bus address. The value of this pin may be used as a counter timer clock input (see Counter Timer Clock Select Register in Chapter 14, Counter/Timers, of the RC32434 User Manual).
GPIO[8]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: CPU Alternate function: CPU or DMA debug output pin.
GPIO[9]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: PCIREQN[4] Alternate function: PCI Request 4.
GPIO[10]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: PCIGNTN[4] Alternate function: PCI Grant 4.
GPIO[11]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: PCIREQN[5] Alternate function: PCI Request 5.
GPIO[12]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: PCIGNTN[5] Alternate function: PCI Grant 5.
GPIO[13]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: PCIMUINTN Alternate function: PCI Messaging unit interrupt output.
SPI Interface		
SCK	I/O	Serial Clock. This signal is used as the serial clock output. This pin may be used as a bit input/output port.

Table 1 Pin Description (Part 4 of 6)

Signal	Type	Name/Description
SDI	I/O	Serial Data Input. This signal is used to shift in serial data. This pin may be used as a bit input/output port.
SDO	I/O	Serial Data Output. This signal is used shift out serial data.
I²C Bus Interface		
SCL	I/O	I²C Clock. I ² C-bus clock.
SDA	I/O	I²C Data Bus. I ² C-bus data bus.
Ethernet Interfaces		
MIICL	I	Ethernet MII Collision Detected. This signal is asserted by the ethernet PHY when a collision is detected.
MIICRS	I	Ethernet MII Carrier Sense. This signal is asserted by the ethernet PHY when either the transmit or receive medium is not idle.
MIIRXCLK	I	Ethernet MII Receive Clock. This clock is a continuous clock that provides a timing reference for the reception of data. This pin also functions as the RMII REF_CLK input.
MIIRXD[3:0]	I	Ethernet MII Receive Data. This nibble wide data bus contains the data received by the ethernet PHY. This pin also functions as the RMII RXD[1:0] input.
MIIRXDV	I	Ethernet MII Receive Data Valid. The assertion of this signal indicates that valid receive data is in the MII receive data bus. This pin also functions as the RMII CRS_DV input.
MIIRXER	I	Ethernet MII Receive Error. The assertion of this signal indicates that an error was detected somewhere in the ethernet frame currently being sent in the MII receive data bus. This pin also functions as the RMII RX_ER input.
MIITXCLK	I	Ethernet MII Transmit Clock. This clock is a continuous clock that provides a timing reference for the transfer of transmit data.
MIITXD[3:0]	O	Ethernet MII Transmit Data. This nibble wide data bus contains the data to be transmitted. This pin also functions as the RMII TXD[1:0] output.
MIITXENP	O	Ethernet MII Transmit Enable. The assertion of this signal indicates that data is present on the MII for transmission. This pin also functions as the RMII TX_EN output.
MIITXER	O	Ethernet MII Transmit Coding Error. When this signal is asserted together with MIITXENP, the ethernet PHY will transmit symbols which are not valid data or delimiters.
MIIMDC	O	MII Management Data Clock. This signal is used as a timing reference for transmission of data on the management interface.
MIIMDIO	I/O	MII Management Data. This bidirectional signal is used to transfer data between the station management entity and the ethernet PHY.
EJTAG / JTAG		
JTAG_TMS	I	JTAG Mode. The value on this signal controls the test mode select of the boundary scan logic or JTAG Controller. When using the EJTAG debug interface, this pin should be left disconnected (since there is an internal pull-up) or driven high.

Table 1 Pin Description (Part 5 of 6)

Function	Pin Name	Type	Buffer	I/O Type	Internal Resistor	Notes ¹
Memory and Peripheral Bus	BDIRN	O	LVTTL	High Drive		
	BOEN	O	LVTTL	High Drive		
	WEN	O	LVTTL	High Drive		
	CSN[3:0]	O	LVTTL	High Drive		
	MADDR[21:0]	I/O	LVTTL	High Drive		
	MDATA[7:0]	I/O	LVTTL	High Drive		
	OEN	O	LVTTL	High Drive		
	RWN	O	LVTTL	High Drive		
	WAITACKN	I	LVTTL	STI	pull-up	
DDR Bus	DDRADDR[13:0]	O	SSTL_2			
	DDRBA[1:0]	O	SSTL_2			
	DDRCASN	O	SSTL_2			
	DDRCKE	O	SSTL_2 / LVC-MOS			
	DDRCKN	O	SSTL_2			
	DDRCKP	O	SSTL_2			
	DDRCASN	O	SSTL_2			
	DDRDATA[15:0]	I/O	SSTL_2			
	DDRDM[1:0]	O	SSTL_2			
	DDRDOQS[1:0]	I/O	SSTL_2			
	DDRRASN	O	SSTL_2			
	DDRVREF	I	Analog			
	DDRWEN	O	SSTL_2			
PCI Bus Interface	PCIAD[31:0]	I/O	PCI			
	PCICBEN[3:0]	I/O	PCI			
	PCICLK	I	PCI			
	PCIDEVSELN	I/O	PCI			pull-up on board
	PCIFRAMEN	I/O	PCI			pull-up on board
	PCIGNTN[3:0]	I/O	PCI			pull-up on board
	PCIIRDYN	I/O	PCI			pull-up on board
	PCILOCKN	I/O	PCI			
	PCIPAR	I/O	PCI			
	PCIPERRN	I/O	PCI			
	PCIREQN[3:0]	I/O	PCI			pull-up on board
	PCIRSTN	I/O	PCI			pull-down on board
	PCISERRN	I/O	PCI	Open Collector		pull-up on board
	PCISTOPN	I/O	PCI			pull-up on board
	PCITRDYN	I/O	PCI			pull-up on board
General Purpose I/O	GPIO[8:0]	I/O	LVTTL	High Drive	pull-up	
	GPIO[13:9]	I/O	PCI			pull-up on board
Serial Peripheral Interface	SCK	I/O	LVTTL	High Drive	pull-up	pull-up on board
	SDI	I/O	LVTTL	High Drive	pull-up	pull-up on board
	SDO	I/O	LVTTL	High Drive	pull-up	pull-up on board
I ² C-Bus Interface	SCL	I/O	LVTTL	Low Drive/STI		pull-up on board ²
	SDA	I/O	LVTTL	Low Drive/STI		pull-up on board ²

Table 2 Pin Characteristics (Part 1 of 2)

Function	Pin Name	Type	Buffer	I/O Type	Internal Resistor	Notes ¹
Ethernet Interfaces	MIICL	I	LVTTL	STI	pull-down	
	MIICRS	I	LVTTL	STI	pull-down	
	MIIRXCLK	I	LVTTL	STI	pull-up	
	MIIRXD[3:0]	I	LVTTL	STI	pull-up	
	MIIRXDV	I	LVTTL	STI	pull-down	
	MIIRXER	I	LVTTL	STI	pull-down	
	MIITXCLK	I	LVTTL	STI	pull-up	
	MIITXD[3:0]	O	LVTTL	Low Drive		
	MIITXENP	O	LVTTL	Low Drive		
	MIITXER	O	LVTTL	Low Drive		
	MIIMDC	O	LVTTL	Low Drive		
	MIIMDIO	I/O	LVTTL	Low Drive	pull-up	
EJTAG / JTAG	JTAG_TMS	I	LVTTL	STI	pull-up	
	EJTAG_TMS	I	LVTTL	STI	pull-up	
	JTAG_TRST_N	I	LVTTL	STI	pull-up	
	JTAG_TCK	I	LVTTL	STI	pull-up	
	JTAG_TDO	O	LVTTL	Low Drive		
	JTAG_TDI	I	LVTTL	STI	pull-up	
System	CLK	I	LVTTL	STI		
	EXTBCV	I	LVTTL	STI	pull-down	
	EXTCLK	O	LVTTL	High Drive		
	COLDRSTN	I	LVTTL	STI		
	RSTN	I/O	LVTTL	Low Drive / STI	pull-up	pull-up on board

Table 2 Pin Characteristics (Part 2 of 2)

¹. External pull-up required in most system applications. Some applications may require additional pull-ups not identified in this table.

². Use a 2.2K pull-up resistor for I2C pins.

Boot Configuration Vector

The encoding of the boot configuration vector is described in Table 3, and the vector input is illustrated in Figure 4. The value of the boot configuration vector read in by the RC32434 during a cold reset may be determined by reading the Boot Configuration Vector (BCV) Register.

Signal	Name/Description
MADDR[3:0]	CPU Pipeline Clock Multiplier. This field specifies the value by which the PLL multiplies the master clock input (CLK) to obtain the processor clock frequency (PCLK). For master clock input frequency constraints, refer to Table 3.2 in the RC32434 User Manual. 0x0 - PLL Bypass 0x1 - Multiply by 3 0x2 - Multiply by 4 0x3 - Multiply by 5 - Reserved 0x4 - Multiply by 5 0x5 - Multiply by 6 - Reserved 0x6 - Multiply by 6 0x7 - Multiply by 8 0x8 - Multiply by 10 0x9 through 0xF - Reserved
MADDR[5:4]	External Clock Divider. This field specifies the value by which the IPBus clock (ICLK), which is always 1/2 PCLK, is divided in order to generate the external clock output on the EXTCLK pin. 0x0 - Divide by 1 0x1 - Divide by 2 0x2 - Divide by 4 0x3 - reserved
MADDR[6]	Endian. This bit specifies the endianness. 0x0 - little endian 0x1 - big endian
MADDR[7]	Reset Mode. This bit specifies the length of time the RSTN signal is driven. 0x0 - Normal reset: RSTN driven for minimum of 4000 clock cycles. If the internal boot configuration vector is selected, the expiration of an 18-bit counter operating at the master clock input (CLK) frequency is used as the PLL stabilization delay. 0x1 - Reserved
MADDR[10:8]	PCI Mode. This bit controls the operating mode of the PCI bus interface. The initial value of the EN bit in the PCIC register is determined by the PCI mode. 0x0 - Disabled (EN initial value is zero) 0x1 - PCI satellite mode with PCI target not ready (EN initial value is one) 0x2 - PCI satellite mode with suspended CPU execution (EN initial value is one) 0x3 - PCI host mode with external arbiter (EN initial value is zero) 0x4 - PCI host mode with internal arbiter using fixed priority arbitration algorithm (EN initial value is zero) 0x5 - PCI host mode with internal arbiter using round robin arbitration algorithm (EN initial value is zero) 0x6 - <i>reserved</i> 0x7 - <i>reserved</i>

Table 3 Boot Configuration Encoding (Part 1 of 2)

AC Timing Definitions

Below are examples of the AC timing characteristics used throughout this document.

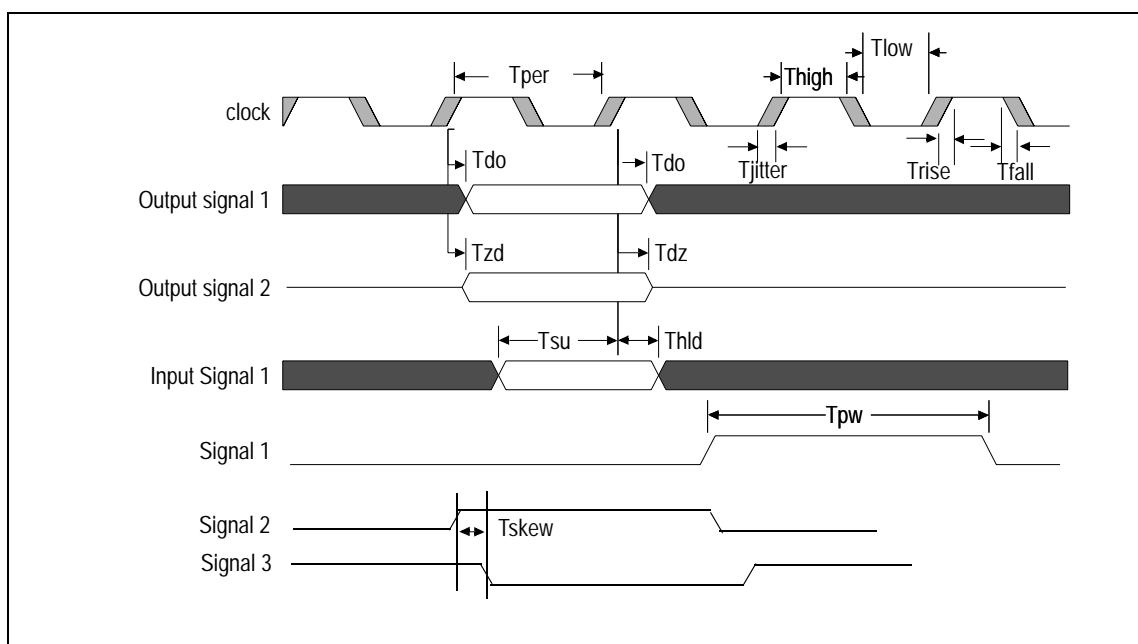


Figure 2 AC Timing Definitions Waveform

Symbol	Definition
Tper	Clock period.
Tlow	Clock low. Amount of time the clock is low in one clock period.
Thigh	Clock high. Amount of time the clock is high in one clock period.
Trise	Rise time. Low to high transition time.
Tfall	Fall time. High to low transition time.
Tjitter	Jitter. Amount of time the reference clock (or signal) edge can vary on either the rising or falling edges.
Tdo	Data out. Amount of time after the reference clock edge that the output will become valid. The minimum time represents the data output hold. The maximum time represents the earliest time the designer can use the data.
Tzd	Z state to data valid. Amount of time after the reference clock edge that the tri-stated output takes to become valid.
Tdz	Data valid to Z state. Amount of time after the reference clock edge that the valid output takes to become tri-stated.
Tsu	Input set-up. Amount of time before the reference clock edge that the input must be valid.
Thld	Input hold. Amount of time after the reference clock edge that the input must remain valid.
Tpw	Pulse width. Amount of time the input or output is active for asynchronous signals.
Tslew	Slew rate. The rise or fall rate for a signal to go from a high to low, or low to high.
X(clock)	Timing value. This notation represents a value of 'X' multiplied by the clock time period of the specified clock. Using 5(CLK) as an example: X = 5 and the oscillator clock (CLK) = 25MHz, then the timing value is 200.
Tskew	Skew. The amount of time two signal edges deviate from one another.

Table 4 AC Timing Definitions

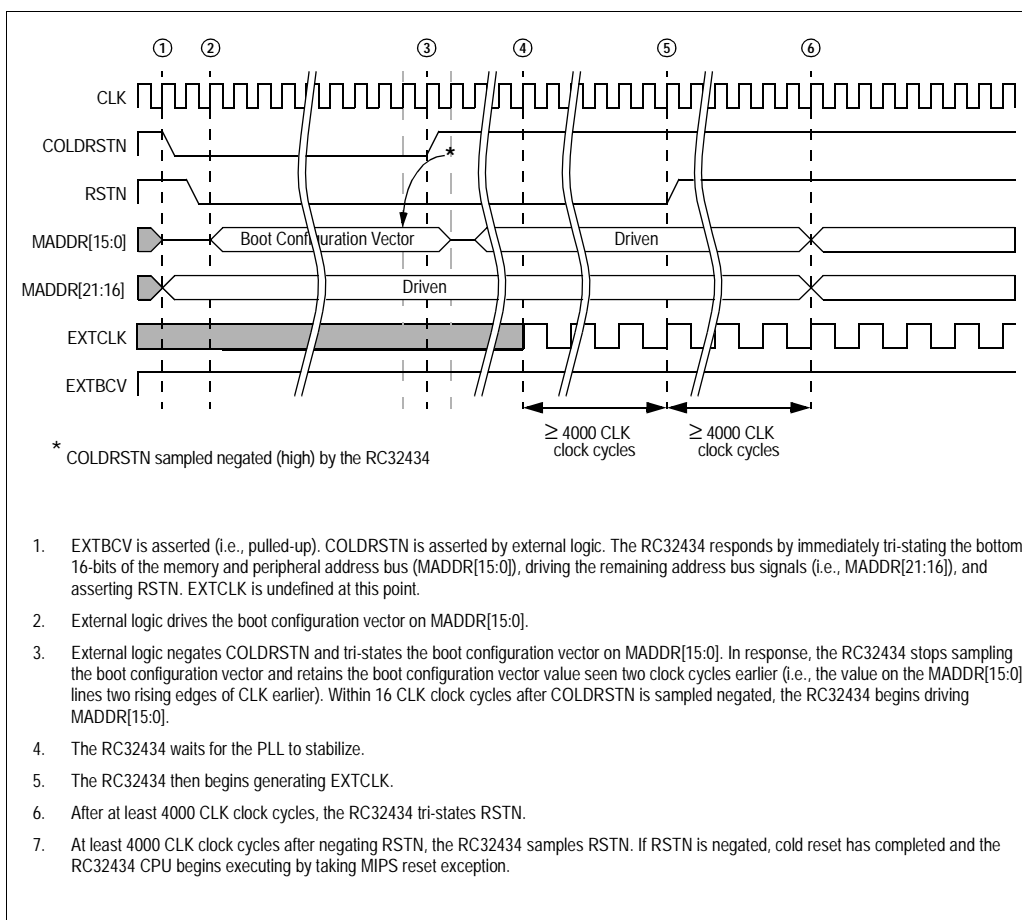


Figure 4 COLD Reset Operation with External Boot Configuration Vector AC Timing Waveform

Note: For a diagram showing the COLD Reset Operation with Internal Boot Configuration Vector, see Figure 3.6 in the RC32434 User Reference Manual.

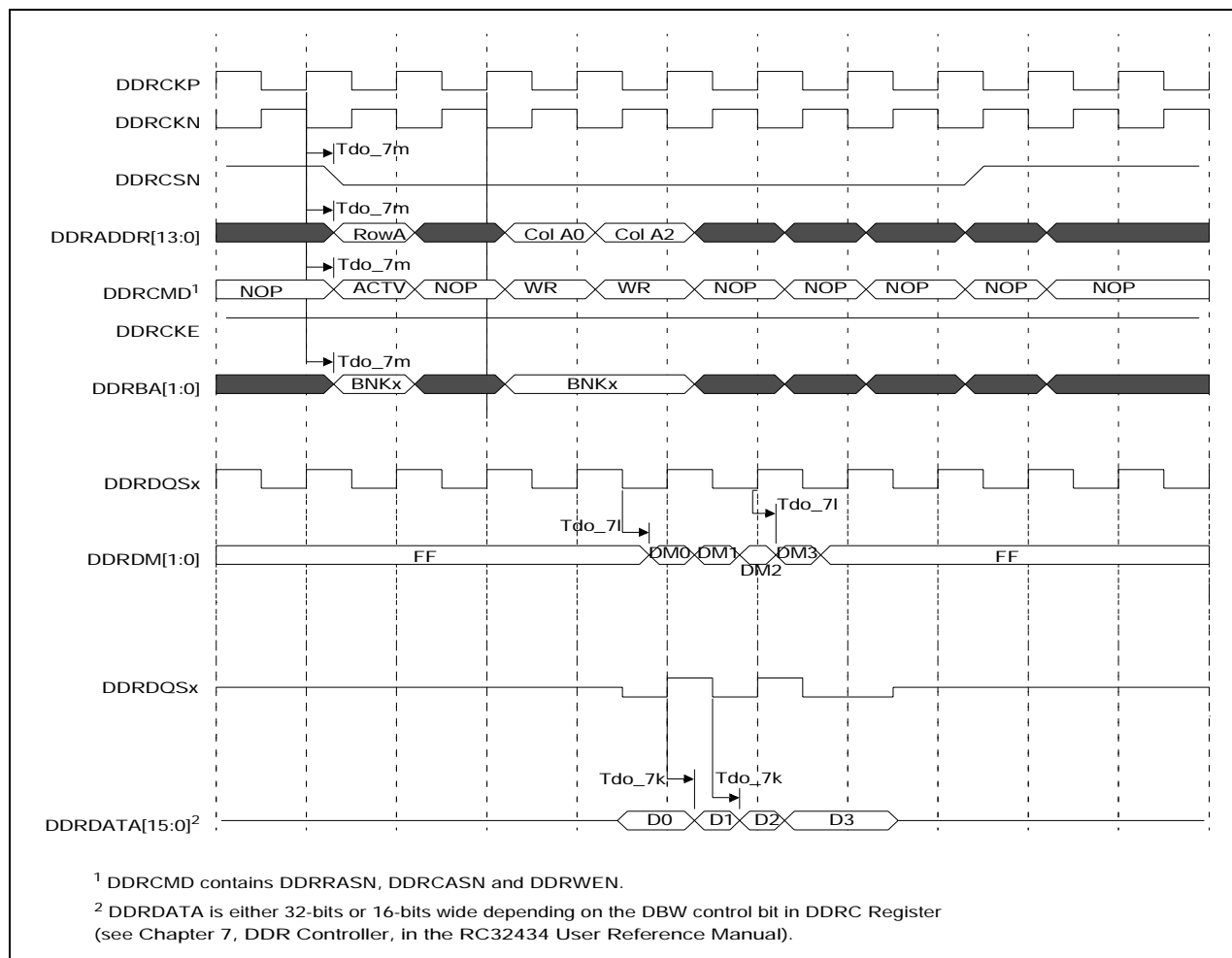


Figure 7 DDR SDRAM Timing Waveform — Write Access

Signal	Symbol	Reference Edge	266MHz		300MHz		350MHz		400MHz		Unit	Condi-tions	Timing Diagram Reference
			Min	Max	Min	Max	Min	Max	Min	Max			
Memory and Peripheral Bus ¹													See Figures 8 and 9.
MADDR[21:0]	Tdo_8a	EXTCLK rising	0.4	4.5	0.4	4.5	0.4	4.5	0.4	4.5	ns		
	Tdz_8a ²		—	—	—	—	—	—	—	—	ns		
	Tzd_8a ²		—	—	—	—	—	—	—	—	ns		
MADDR[25:22]	Tdo_8b	EXTCLK rising	0.4	4.5	0.4	4.5	0.4	4.5	0.4	4.5	ns		
	Tdz_8b ²		—	—	—	—	—	—	—	—	ns		
	Tzd_8b ²		—	—	—	—	—	—	—	—	ns		

Table 8 Memory and Peripheral Bus AC Timing Characteristics (Part 1 of 2)

Signal	Symbol	Reference Edge	266MHz		300MHz		350MHz		400MHz		Unit	Condi- tions	Timing Diagram Reference
			Min	Max	Min	Max	Min	Max	Min	Max			
MDATA[7:0]	Tsu_8c	EXTCLK rising	6.0	—	6.0	—	6.0	—	6.0	—	ns		See Figures 8 and 9 (cont.).
	Thld_8c		0	—	0	—	0	—	0	—	ns		
	Tdo_8c		0.4	4.5	0.4	4.5	0.4	4.5	0.4	4.5	ns		
	Tdz_8c ²		0	0.5	0	0.5	0	0.5	0	0.5	ns		
	Tzd_8c ²		0.4	3.3	0.4	3.3	0.4	3.3	0.4	3.3	ns		
EXTCLK ³	Tper_8d	none	7.5	—	6.66	—	6.66	—	6.66	—	ns		
BDIRN	Tdo_8e	EXTCLK rising	0.4	3.8	0.4	3.8	0.4	3.8	0.4	3.8	ns		
	Tdz_8e ²		—	—	—	—	—	—	—	—	ns		
	Tzd_8e ²		—	—	—	—	—	—	—	—	ns		
BOEN	Tdo_8f	EXTCLK rising	0.4	3.8	0.4	3.8	0.4	3.8	0.4	3.8	ns		
	Tdz_8f ²		—	—	—	—	—	—	—	—	ns		
	Tzd_8f ²		—	—	—	—	—	—	—	—	ns		
WAITACKN ⁴	Tsu_8h	EXTCLK rising	6.5	—	6.5	—	6.5	—	6.5	—	ns		
	Thld_8h		0	—	0	—	0	—	0	—	ns		
	Tpw_8h ²	none	2(EXTCLK)	—	2(EXTCLK)	—	2(EXTCLK)	—	2(EXTCLK)	—	ns		
CSN[3:0]	Tdo_8i	EXTCLK rising	0.4	4.0	0.4	4.0	0.4	4.0	0.4	4.0	ns		
	Tdz_8i ²		—	—	—	—	—	—	—	—	ns		
	Tzd_8i ²		—	—	—	—	—	—	—	—	ns		
RWN	Tdo_8j	EXTCLK rising	0.4	3.8	0.4	3.8	0.4	3.8	0.4	3.8	ns		
	Tdz_8j ²		—	—	—	—	—	—	—	—	ns		
	Tzd_8j ²		—	—	—	—	—	—	—	—	ns		
OEN	Tdo_8k	EXTCLK rising	0.4	4.0	0.4	4.0	0.4	4.0	0.4	4.0	ns		
	Tdz_8k ²		—	—	—	—	—	—	—	—	ns		
	Tzd_8k ²		—	—	—	—	—	—	—	—	ns		
WEN	Tdo_8l	EXTCLK rising	0.4	3.7	0.4	3.7	0.4	3.7	0.4	3.7	ns		
	Tdz_8l ²		—	—	—	—	—	—	—	—	ns		
	Tzd_8l ²		—	—	—	—	—	—	—	—	ns		

Table 8 Memory and Peripheral Bus AC Timing Characteristics (Part 2 of 2)

¹. The RC32434 provides bus turnaround cycles to prevent bus contention when going from read to write, write to read, and during external bus ownership. For example, there are no cycles where an external device and the RC32434 are both driving. See Chapter 6, Device Controller, in the RC32434 User Reference Manual.

². The values for this symbol were determined by calculation, not by testing.

³. The frequency of EXTCLK is programmable. See the External Clock Divider (MDATA[5:4]) description in Table 3 of this data sheet.

⁴. WAITACKN must meet the setup and hold times if it is synchronous or the minimum pulse width if it is asynchronous.

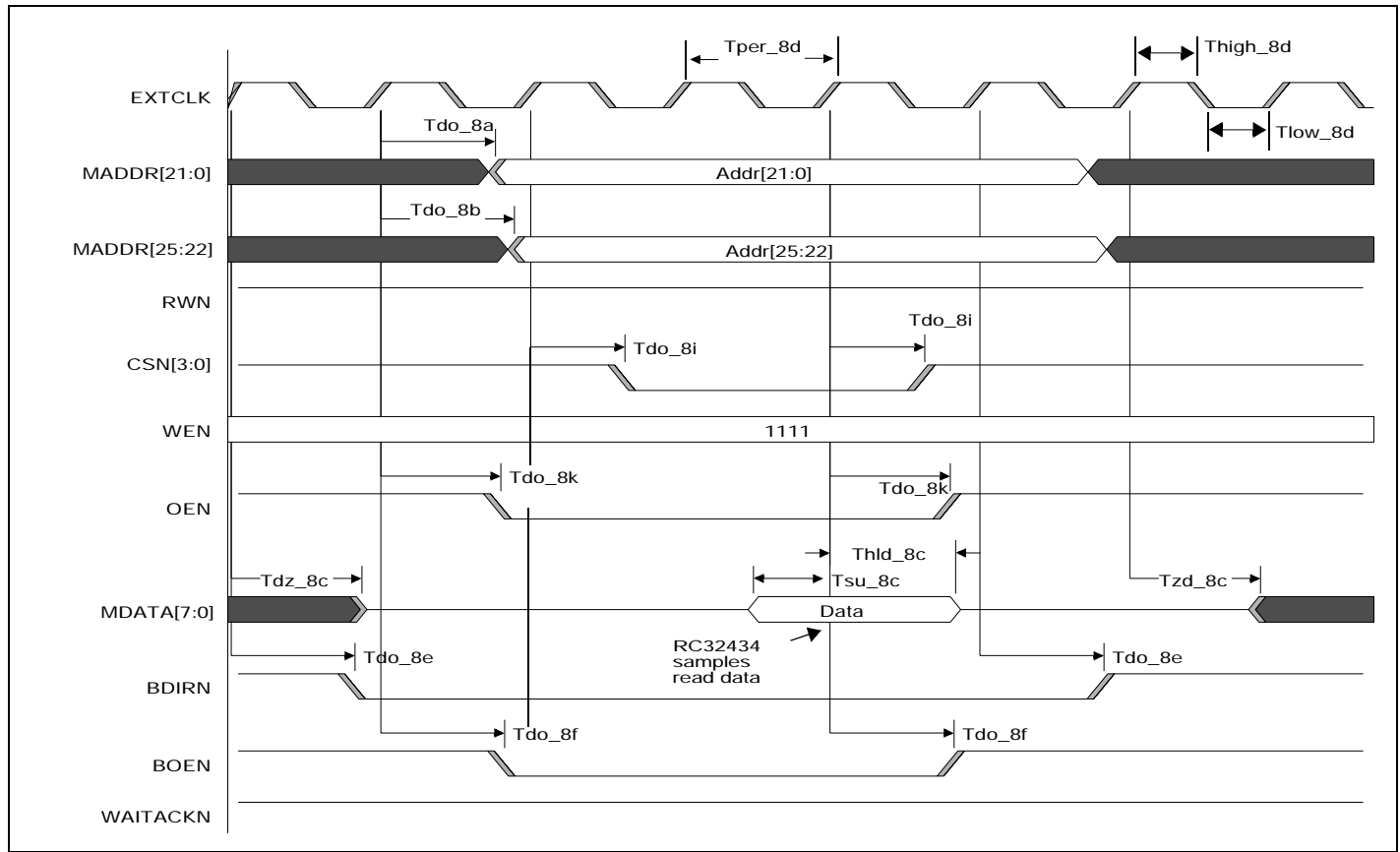


Figure 8 Memory and Peripheral Bus AC Timing Waveform — Read Access

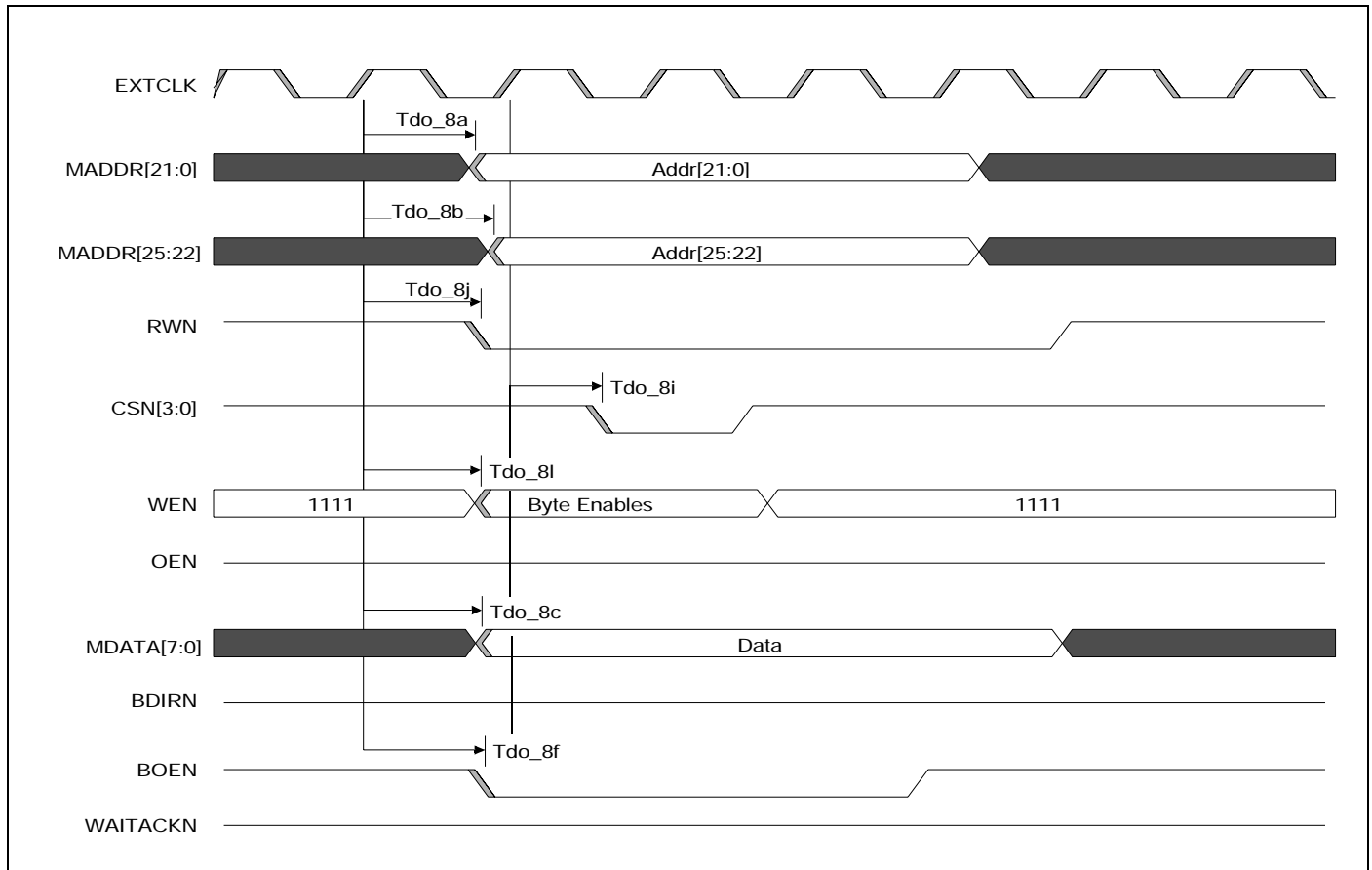


Figure 9 Memory and Peripheral Bus AC Timing Waveform — Write Access

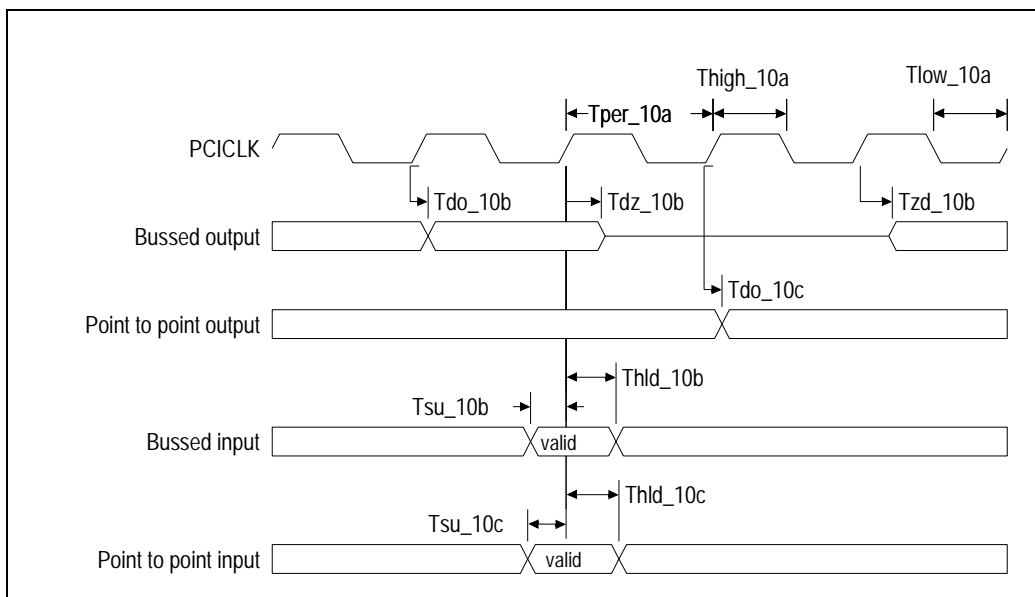


Figure 11 PCI AC Timing Waveform

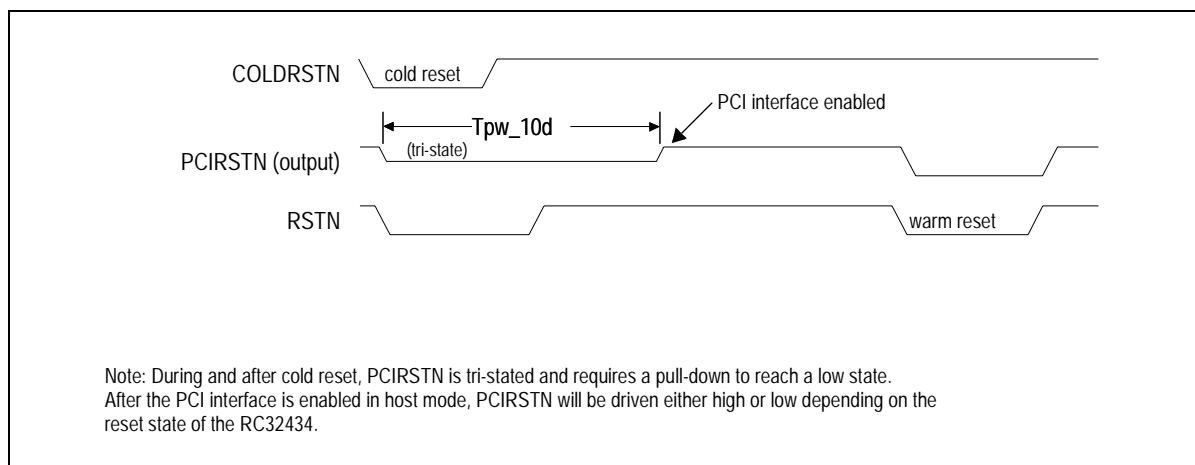


Figure 12 PCI AC Timing Waveform — PCI Reset in Host Mode

Signal	Symbol	Reference Edge	266MHz		300MHz		350MHz		400MHz		Unit	Conditions	Timing Diagram Reference
			Min	Max	Min	Max	Min	Max	Min	Max			
Start or repeated start condition	Tsu_12c	SDA falling	0.6	—	0.6	—	0.6	—	0.6	—	µs	400 KHz	See Figure 14.
	Thld_12c		0.6	—	0.6	—	0.6	—	0.6	—	µs		
Stop condition	Tsu_12d	SDA rising	0.6	—	0.6	—	0.6	—	0.6	—	µs		
Bus free time between a stop and start condition	Tdelay_12e		1.3	—	1.3	—	1.3	—	1.3	—	µs		

Table 11 I²C AC Timing Characteristics (Part 2 of 2)

¹. For more information, see the I²C-Bus specification by Philips Semiconductor.

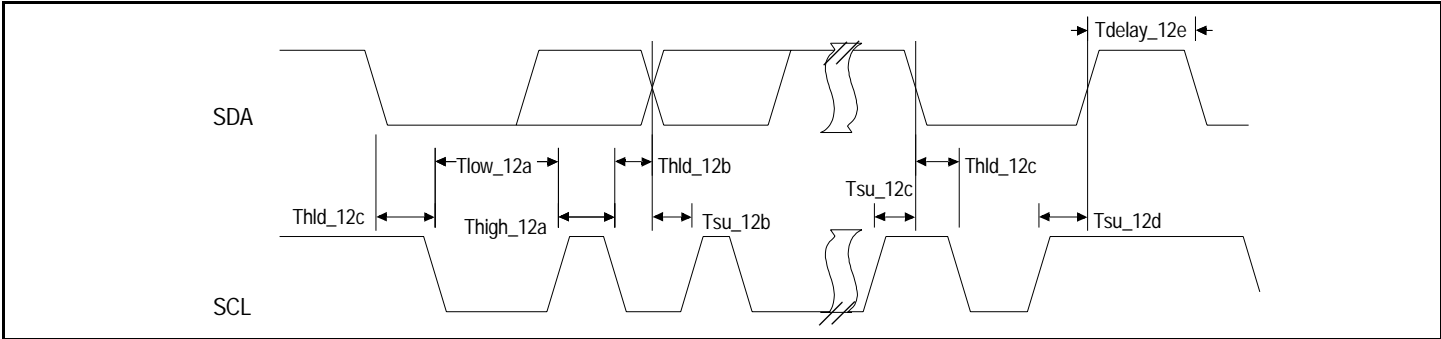


Figure 14 I2C AC Timing Waveform

Signal	Symbol	Reference Edge	266MHz		300MHz		350MHz		400MHz		Unit	Condi-tions	Timing Diagram Reference
			Min	Max	Min	Max	Min	Max	Min	Max			
GPIO													
GPIO[13:0]	Tpw_13b ¹	None	2(ICLK)	—	2(ICLK)	—	2(ICLK)	—	2(ICLK)	—	ns		See Figure 15.

Table 12 GPIO AC Timing Characteristics

¹. The values for this symbol were determined by calculation, not by testing.

1

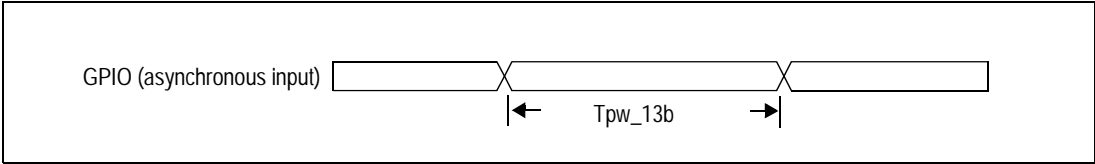


Figure 15 GPIO AC Timing Waveform

Pin	Function	Alt	Pin	Function	Alt	Pin	Function	Alt	Pin	Function	Alt
C2	BDIRN		G2	MIITXER		L2	SCL		R2	PCICBEN[3]	
C3	COLDRSTN		G3	MIIRXER		L3	GPIO[8]	1	R3	PCIAD[23]	
C4	WEN		G4	MIITXCLK		L4	SDI		R4	PCIAD[21]	
C5	MDATA[3]		G5	V _{cc} I/O		L5	V _{cc} I/O		R5	PCIAD[17]	
C6	MDATA[5]		G6	V _{ss}		L6	V _{ss}		R6	PCIRSTN	
C7	GPIO[6]	1	G7	V _{ss}		L7	V _{ss}		R7	PCICBEN[2]	
C8	MADDR[21]		G8	V _{ss}		L8	V _{cc} CORE		R8	PCITRDYN	
C9	MADDR[18]		G9	V _{ss}		L9	V _{ss}		R9	PCICBEN[1]	
C10	MADDR[14]		G10	V _{ss}		L10	V _{ss}		R10	PCIAD[12]	
C11	JTAG_TMS		G11	V _{ss}		L11	V _{ss}		R11	PCIAD[8]	
C12	V _{cc} APLL		G12	V _{cc} DDR		L12	V _{cc} DDR		R12	PCIAD[5]	
C13	CLK		G13	DDRDM[1]		L13	DDRADDR[9]		R13	PCIAD[3]	
C14	MADDR[4]		G14	DDRQDS[1]		L14	DDRWEN		R14	PCIAD[0]	
C15	MADDR[0]		G15	DDRDATA[10]		L15	DDRCASN		R15	PCIGNTN[2]	
C16	DDRDATA[0]		G16	DDRDATA[11]		L16	DDRADDR[8]		R16	DDRADDR[1]	
D1	MIIRXD[0]		H1	MIIMDIO		M1	GPIO[12]	1	T1	PCIAD[24]	
D2	MIICL		H2	MIIMDC		M2	PCIAD[31]		T2	GPIO[13]	1
D3	MIICRS		H3	GPIO[0]	1	M3	GPIO[11]	1	T3	PCIAD[22]	
D4	MIIRXD[1]		H4	GPIO[1]	1	M4	GPIO[9]	1	T4	PCIAD[19]	
D5	MDATA[7]		H5	V _{cc} CORE		M5	V _{cc} I/O		T5	PCIAD[16]	
D6	MDATA[2]		H6	V _{cc} CORE		M6	V _{cc} I/O		T6	PCICLK	
D7	MDATA[0]		H7	V _{ss}		M7	V _{cc} I/O		T7	PCIGNTN[0]	
D8	MADDR[20]		H8	V _{ss}		M8	V _{cc} CORE		T8	PCIDEVSELN	
D9	MADDR[19]		H9	V _{ss}		M9	V _{cc} CORE		T9	PCIPAR	
D10	MADDR[15]		H10	V _{ss}		M10	V _{cc} I/O		T10	PCIAD[13]	
D11	EXTBCV		H11	V _{ss}		M11	V _{cc} DDR		T11	PCIAD[9]	
D12	JTAG_TRSTN		H12	V _{cc} CORE		M12	V _{cc} DDR		T12	PCIAD[6]	
D13	WAITACKN		H13	DDRDATA[15]		M13	DDRRASN		T13	PCIAD[2]	
D14	DDRDATA[2]		H14	DDRDATA[14]		M14	DDRBA[1]		T14	PCIAD[1]	
D15	DDRDATA[3]		H15	DDRDATA[12]		M15	DDRADDR[6]		T15	PCIGNTN[1]	
D16	DDRDATA[1]		H16	DDRDATA[13]		M16	DDRADDR[7]		T16	PCIGNTN[3]	

Table 20 RC32434 Pinout (Part 2 of 2)

RC32434 Alternate Signal Functions

Pin	GPIO	Alternate	Pin	GPIO	Alternate
A7	GPIO[7]	MADDR[25]	J3	GPIO[2]	U0RTSN
A8	GPIO[4]	MADDR[22]	L3	GPIO[8]	CPU
B8	GPIO[5]	MADDR[23]	M1	GPIO[12]	PCIGNTN[5]
C7	GPIO[6]	MADDR[24]	M3	GPIO[11]	PCIREQN[5]
H3	GPIO[0]	U0SOUT	M4	GPIO[9]	PCIREQN[4]
H4	GPIO[1]	U0SINP	P3	GPIO[10]	PCIGNTN[4]
J1	GPIO[3]	U0CTSN	T2	GPIO[13]	PCIMUINTN

Table 21 RC32434 Alternate Signal Functions

RC32434 Power Pins

V _{CC} I/O	V _{CC} DDR	V _{CC} Core	V _{CC} PLL	V _{CC} APLL
E5	E11	E8	B11	C12
E6	E12	E9		
E7	F12	F9		
E10	G12	H5		
F5	K12	H6		
G5	L12	H12		
K5	M11	J5		
K6	M12	J11		
L5		J12		
M5		L8		
M6		M8		
M7		M9		
M10				

Table 22 RC32434 Power Pins

Signal Name	I/O Type	Location	Signal Category
DDRADDR[0]	O	P14	DDR Bus
DDRADDR[1]	O	R16	
DDRADDR[2]	O	P15	
DDRADDR[3]	O	N15	
DDRADDR[4]	O	N14	
DDRADDR[5]	O	N13	
DDRADDR[6]	O	M15	
DDRADDR[7]	O	M16	
DDRADDR[8]	O	L16	
DDRADDR[9]	O	L13	
DDRADDR[10]	O	K15	
DDRADDR[11]	O	K14	
DDRADDR[12]	O	K16	
DDRADDR[13]	O	E15	
DDRBA[0]	O	N16	
DDRBA[1]	O	M14	
DDRCASN	O	L15	
DDRCKE	O	K13	
DDRCKN	O	J13	
DDRCKP	O	J15	
DDRCSN	O	P16	
DDRDATA[0]	I/O	C16	
DDRDATA[1]	I/O	D16	
DDRDATA[2]	I/O	D14	
DDRDATA[3]	I/O	D15	
DDRDATA[4]	I/O	E16	
DDRDATA[5]	I/O	E14	
DDRDATA[6]	I/O	E13	
DDRDATA[7]	I/O	F16	
DDRDATA[8]	I/O	F14	
DDRDATA[9]	I/O	F13	
DDRDATA[10]	I/O	G15	
DDRDATA[11]	I/O	G16	
DDRDATA[12]	I/O	H15	
DDRDATA[13]	I/O	H16	
DDRDATA[14]	I/O	H14	

Table 24 RC32434 Alphabetical Signal List (Part 2 of 7)

Signal Name	I/O Type	Location	Signal Category
DDRDATA[15]	I/O	H13	DDR Bus
DDRDM[0]	O	F15	
DDRDM[1]	O	G13	
DDRDSQ[0]	I/O	J16	
DDRDSQ[1]	I/O	G14	
DDRRASN	O	M13	
DDRVREF	I	J14	
DDRWEN	O	L14	
EJTAG_TMS	I	J4	JTAG / EJTAG
EXTBCV	I	D11	System
EXTCLK	O	C1	
GPIO[0]	I/O	H3	General Purpose Input/Output
GPIO[1]	I/O	H4	
GPIO[2]	I/O	J3	
GPIO[3]	I/O	J1	
GPIO[4]	I/O	A8	
GPIO[5]	I/O	B8	
GPIO[6]	I/O	C7	
GPIO[7]	I/O	A7	
GPIO[8]	I/O	L3	
GPIO[9]	I/O	M4	
GPIO[10]	I/O	P3	
GPIO[11]	I/O	M3	
GPIO[12]	I/O	M1	
GPIO[13]	I/O	T2	
JTAG_TCK	I	J2	JTAG / EJTAG
JTAG_TDI	I	A12	
JTAG_TDO	O	K1	
JTAG_TMS	I	C11	
JTAG_TRSTN	I	D12	

Table 24 RC32434 Alphabetical Signal List (Part 3 of 7)

Ordering Information

79RCXX	YY	XXXX	999	A	A	
Product Type	Operating Voltage	Device Type	Speed	Package	Temp range/ Process	
					Blank	Commercial Temperature (0°C to +70°C Ambient)
					I	Industrial Temperature (-40° C to +85° C Ambient)
				BC		256-pin CABGA
			266			266 MHz Pipeline Clk
			300			300 MHz Pipeline Clk
			350			350 MHz Pipeline Clk
			400			400 MHz Pipeline Clk
		434				Integrated Core Processor
	H					1.2V +/- 0.1V Core Voltage
					79RC32	32-bit Embedded Microprocessor

Valid Combinations

79RC32H434 - 266BC, 300BC, 350BC, 400BC

256-pin CABGA package, Commercial Temperature

79RC32H434 - 266BCI, 300BCI, 350BCI

256-pin CABGA package, Industrial Temperature



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